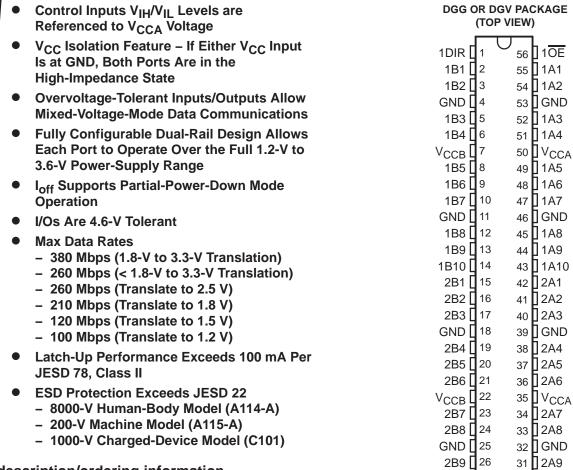
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description/ordering information

This 20-bit noninverting bus transceiver uses two separate configurable power-supply rails.

The SN74AVC20T245 is optimized to operate with V_{CCA}/V_{CCB} set at 1.4 V to 3.6 V. It is operational with V_{CCA}/V_{CCB} as low as 1.2 V. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

2B10 27

2DIR [] 28

30 2A10

29 20E

ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	TSSOP - DGG	Tape and reel	SN74AVC20T245DGGR	AVC20T245
40°C to 95°C	TVSOP - DGV	Tape and reel	SN74AVC20T245DGVR	WG245
–40°C to 85°C	VFBGA – GQL	Tono and roal	SN74AVC20T245GQLR	WG245
	VFBGA – ZQL (Pb-free)	Tape and reel	SN74AVC20T245ZQLR	WG245

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description/ordering information (continued)

The SN74AVC20T245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input is used to disable the outputs so that the buses are isolated.

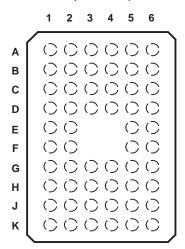
The SN74AVC20T245 is designed so that the control (1DIR, 2DIR, 1OE, and 2OE) inputs are supplied by V_{CCA}.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, both ports are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

GQL OR ZQL PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4	5	6
Α	1B1	1B2	1DIR	1OE	1A2	1A1
В	1B3	1B4	GND	GND	1A4	1A3
С	1B5	1B6	VCCB	VCCA	1A6	1A5
D	1B7	1B8	GND	GND	1A8	1A7
E	1B9	1B10			1A10	1A9
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	VCCB	VCCA	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2B9	2B10	2DIR	2 <mark>OE</mark>	2A10	2A9

FUNCTION TABLE (each 10-bit section)

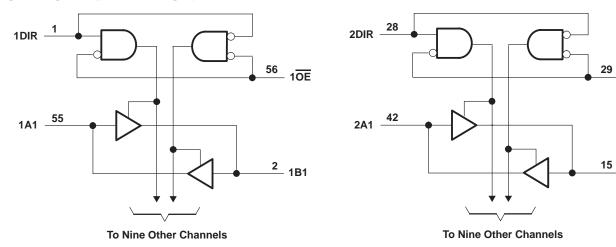
INP	UTS					
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	Χ	Isolation				

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20E

2B1

logic diagram (positive logic)



Pin numbers shown are for the DGG and DGV packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range, V _I (see Note 1): I/O ports (A po	-0.5 V to 4.6 V ort) -0.5 V to 4.6 V ort) -0.5 V to 4.6 V
·	6
Voltage range applied to any output in the high-imp	
(B port)	
Voltage range applied to any output in the high or lo	ow state, V _O
(see Notes 1 and 2): (A port)	0.5 V to V _{CCA} + 0.5 V
	0.5 V to V _{CCB} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
	–50 mA
	±50 mA
	d GND ±100 mA
Package thermal impedance, θ _{.IA} (see Note 3): DG	GG package 64°C/W
	GV package 48°C/W
	QL/ZQL package 42°C/W
	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Notes 4 through 8)

			VCCI	Vcco	MIN	MAX	UNIT
V _{CCA}	Supply voltage				1.2	3.6	V
V _{CCB}	Supply voltage				1.2	3.6	V
		5	1.2 V to 1.95 V		V _{CCI} × 0.65		
VIΗ	High-level input voltage	Data inputs (see Note 7)	1.95 V to 2.7 V		1.6		V
	voltage	(500 14010 7)	2.7 V to 3.6 V		2		
		5	1.2 V to 1.95 V			$V_{CCI} \times 0.35$	
VIL	Low-level input voltage	Data inputs (see Note 7)	1.95 V to 2.7 V			0.7	V
		(655 11615 1)	2.7 V to 3.6 V			0.8	
	LP ab Java Canad	DIR	1.2 V to 1.95 V		$V_{CCA} \times 0.65$		
V_{IH}	High-level input voltage	(referenced to V _{CCA})	1.95 V to 2.7 V		1.6		V
	vokago	(see Note 8)	2.7 V to 3.6 V		2		
		DIR	1.2 V to 1.95 V			$V_{\text{CCA}} \times 0.35$	
\vee_{IL}	Low-level input voltage	(referenced to VCCA)	1.95 V to 2.7 V			0.7	V
	vokago	(see Note 8)	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
\/-	Output valtage	Active state			0	Vcco	V
VO	Output voltage	3-state			0	3.6	V
				1.2 V		-3	
				1.4 V to 1.6 V		-6	
ЮН	High-level output curre	nt		1.65 V to 1.95 V		-8	mA
				2.3 V to 2.7 V		-9	
				3 V to 3.6 V		-12	
				1.2 V		3	
				1.4 V to 1.6 V		6	
lOL	Low-level output currer	nt		1.65 V to 1.95 V		8	mA
				2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt/Δν	Input transition rise or f	all rate				5	ns/V
TA	Operating free-air temp	perature			-40	85	°C

NOTES: 4. V_{CCI} is the V_{CC} associated with the data input port.

- 5. V_{CCO} is the V_{CC} associated with the output port.
- 6. All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
- 7. For V_{CCI} values not specified in the data sheet, V_{IH(min)} = V_{CCI} x 0.7 V, V_{IL(max)} = V_{CCI} x 0.3 V.

 8. For V_{CCI} values not specified in the data sheet, V_{IH(min)} = V_{CCA} x 0.7 V, V_{IL(max)} = V_{CCA} x 0.3 V.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Notes 9 and 10)

		TEGT CONDIT	10110	.,	,,	T	λ = 25°C	;	-40°C to	85°C	LINIT
PARA	METER	TEST CONDIT	IONS	VCCA	VCCB	MIN	TYP	MAX	MIN	MAX	UNIT
		$I_{OH} = -100 \mu A$		1.2 V to 3.6 V	1.2 V to 3.6 V				Vcco-	0.2 V	
		$I_{OH} = -3 \text{ mA}$		1.2 V	1.2 V		0.95				
.,		$I_{OH} = -6 \text{ mA}$],, ,,	1.4 V	1.4 V				1.05		.,
VOH		$I_{OH} = -8 \text{ mA}$	$V_I = V_{IH}$	1.65 V	1.65 V				1.2		V
		$I_{OH} = -9 \text{ mA}$		2.3 V	2.3 V				1.75		
		$I_{OH} = -12 \text{ mA}$		3 V	3 V				2.3		
		I _{OL} = 100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V					0.2	
		I _{OL} = 3 mA		1.2 V	1.2 V		0.15				
.,		I _{OL} = 6 mA],, ,,	1.4 V	1.4 V					0.35	.,
VOL		I _{OL} = 8 mA	VI = VIL	1.65 V	1.65 V					0.45	V
		I _{OL} = 9 mA		2.3 V	2.3 V					0.55	
		I _{OL} = 12 mA		3 V	3 V					0.7	
II	Control inputs	$V_I = V_{CCA}$ or GND		1.2 V to 3.6 V	1.2 V to 3.6 V	:	±0.025	±0.25		±1	μΑ
	A or B port	N	,	0 V	0 to 3.6 V		±0.1	±1		±5	
l _{off}	A or B port	V_I or $V_O = 0$ to 3.6 $^{\circ}$	V	0 to 3.6 V	0 V		±0.1	±1		±5	μΑ
I _{OZ} †	A or B ports	$V_O = V_{CCO}$ or GND, $V_I = V_{CCI}$ or GND	OE = VIH	3.6 V	3.6 V		±0.5	±2.5		±5	μА
				1.2 V to 3.6 V	1.2 V to 3.6 V					35	
ICCA		$V_I = V_{CCI}$ or GND,	$I_O = 0$	0 V	3.6 V					-5	μΑ
				3.6 V	0 V					35	
				1.2 V to 3.6 V	1.2 V to 3.6 V					35	
ICCB		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	0 V	3.6 V					35	μΑ
			-	3.6 V	0 V					-5	
ICCA	+ ICCB	$V_I = V_{CCI}$ or GND,	IO = 0	1.2 V to 3.6 V	1.2 V to 3.6 V					65	μΑ
Ci	Control inputs	V _I = 3.3 V or GND		3.3 V	3.3 V		3.5				pF
C _{io}	A or B ports	V _O = 3.3 V or GND		3.3 V	3.3 V		7				pF

 $\ensuremath{^{\dagger}}$ For I/O ports, the parameter IOZ includes the input leakage current.

NOTES: 9. V_{CCO} is the V_{CC} associated with the output port.

10. V_{CCI} is the V_{CC} associated with the input port.



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switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.2 \text{ V}$ (see Figure 1)

242445752	FROM	то	V _{CCB} = 1.2 V	V _{CCB} = 1.5 V	V _{CCB} = 1.8 V	V _{CCB} = 2.5 V	V _{CCB} = 3.3 V									
PARAMETER	(INPUT)	(OUTPUT)	TYP	TYP	TYP	TYP	TYP	UNIT								
t _{PLH}	٨		3.8	3.1	2.8	2.7	3.3									
t _{PHL}	Α	В	3.8	3.1	2.8	2.7	3.3	ns								
t _{PLH}	1		4.1	3.8	3.6	3.5	3.4									
t _{PHL}	В	А	4.1	3.8	3.6	3.5	3.4	ns								
^t PZH	ŌĒ		6.5	6.5	6.5	6.5	6.5									
tPZL	OE	А	6.5	6.5	6.5	6.5	6.5	ns								
^t PZH	ŌĒ		5.6	4.4	3.8	3.3	3.2									
tPZL	OE	В	5.6	4.4	3.8	3.3	3.2	ns								
t _{PHZ}	ŌĒ		6.4	6.4	6.4	6.4	6.4									
tPLZ	OE	А	6.4	6.4	6.4	6.4	6.4	ns								
t _{PHZ}	<u> </u>		5.7	4.6	4.7	4.1	5.4									
t _{PLZ}	OE	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	5.7	4.6	4.7	4.1	5.4	ns	

switching characteristics over recommended operating free-air temperature range, V_{CCA} = 1.5 V \pm 0.1 V (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V	V _{CCB} = ± 0.7		V _{CCB} = ± 0.1		V _{CCB} = ± 0.2		V _{CCB} = ± 0.5		UNIT																				
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX																					
tPLH	٨		3.8	0.5	6.4	0.5	5.4	0.5	4.3	0.5	3.9																					
t _{PHL}	Α	В	3.8	0.5	6.4	0.5	5.4	0.5	4.3	0.5	3.9	ns																				
t _{PLH}		A	3.1	0.5	6.4	0.5	6.1	0.5	5.8	0.5	5.7																					
t _{PHL}	В	Α	A	3.1	0.5	6.4	0.5	6.1	0.5	5.8	0.5	5.7	ns																			
t _{PZH}	ŌĒ	A	4.3	1.5	10.3	1.5	10.3	1.5	10.2	1.5	10.2																					
tPZL	OE	Α	4.3	1.5	10.3	1.5	10.3	1.5	10.2	1.5	10.2	ns																				
t _{PZH}	ŌĒ		5.2	1	10.3	1	8.4	0.5	6.1	0.5	5.3																					
tPZL	OE	В	5.2	1	10.3	1	8.4	0.5	6.1	0.5	5.3	ns																				
t _{PHZ}			4.5	2	9	2	9	2	9	2	9																					
t _{PLZ}	ŌĒ	A	4.5	2	9	2	9	2	9	2	9	ns																				
t _{PHZ}	ŌĒ	<u> </u>	5.1	1.5	9	1.5	7.8	1	6.4	1	5.9																					
tPLZ		ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	5.1	1.5	9	1.5	7.8	1	6.4	1	5.9

SN74AVC20T245 20-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES566F - MAY 2004 - REVISED APRIL 2005

switching characteristics over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V	V _{CCB} =		V _{CCB} = ± 0.1		V _{CCB} =		V _{CCB} =		UNIT																						
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX																							
t _{PLH}	А	В	3.6	0.5	6.1	0.5	5	0.5	3.9	0.5	3.5																							
t _{PHL}	А	В	3.6	0.5	6.1	0.5	5	0.5	3.9	0.5	3.5	ns																						
t _{PLH}	В		2.8	0.5	5.4	0.5	5	0.5	4.7	0.5	4.6																							
t _{PHL}	В	Α	2.8	0.5	5.4	0.5	5	0.5	4.7	0.5	4.6	ns																						
^t PZH	ŌĒ		3.4	1	8.1	1	7.9	1	7.9	1	7.9																							
t _{PZL}	OE	Α	3.4	1	8.1	1	7.9	1	7.9	1	7.9	ns																						
^t PZH	ŌĒ		5	0.5	10	0.5	7.9	0.5	5.7	0.5	4.8																							
t _{PZL}	OE	В	5	0.5	10	0.5	7.9	0.5	5.7	0.5	4.8	ns																						
t _{PHZ}		Δ.	4.1	2	7.4	2	7.4	2	7.4	2	7.4																							
t _{PLZ}	OE A	4.1	2	7.4	2	7.4	2	7.4	2	7.4	ns																							
t _{PHZ}	<u> </u>			4.9	1.5	8.7	1.5	7.4	1	5.8	1	5.1																						
t _{PLZ}	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	DE В	4.9	1.5	8.7	1.5	7.4	1	5.8	1	5.1	ns

switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 2.5 V \pm 0.2 V$ (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V	V _{CCB} =		V _{CCB} = ± 0.1		V _{CCB} = ± 0.		V _{CCB} =		UNIT																	
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX																		
tPLH	Δ.		3.5	0.5	5.8	0.5	4.7	0.5	3.5	0.5	3																		
tPHL	Α	В	3.5	0.5	5.8	0.5	4.7	0.5	3.5	0.5	3	ns																	
tPLH	0	Δ.	2.7	0.5	4.3	0.5	3.9	0.5	3.5	0.5	3.4																		
t _{PHL}	В	А	2.7	0.5	4.3	0.5	3.9	0.5	3.5	0.5	3.4	ns																	
^t PZH	ŌĒ	Δ.	2.5	0.5	5.4	0.5	5.3	0.5	5.2	0.5	5.2																		
tPZL	OE	Α	2.5	0.5	5.4	0.5	5.3	0.5	5.2	0.5	5.2	ns																	
^t PZH	ŌĒ	В	4.8	0.5	9.6	0.5	7.6	0.5	5.3	0.5	4.3	20																	
tPZL	OE	В	4.8	0.5	9.6	0.5	7.6	0.5	5.3	0.5	4.3	ns																	
t _{PHZ}		Δ.	3	1.1	5.2	1.1	5.2	1.1	5.2	1.1	5.2																		
tPLZ	OE	ŌE A	3	1.1	5.2	1.1	5.2	1.1	5.2	1.1	5.2	ns																	
t _{PHZ}	<u> </u>	ŌĒ	ŌĒ	ŌĒ	ŌĒ	<u> </u>	<u> </u>	<u> </u>		<u></u>	<u> </u>	<u> </u>	<u> </u>		<u> </u>	<u> </u>	<u> </u>		ŌĒ B	4.7	1.2	8.2	1.2	6.9	1	5.3	1	5	
t _{PLZ}	ŌĒ					В	4.7	1.2	8.2	1.2	6.9	1	5.3	1	5	ns													

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switching characteristics over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V	VCCB =		V _{CCB} = ± 0.1		V _{CCB} = ± 0.2		V _{CCB} =		UNIT																			
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX																				
tPLH	٨	В	3.4	0.5	5.7	0.5	4.6	0.5	3.4	0.5	2.9																				
tPHL	Α	В	3.4	0.5	5.7	0.5	4.6	0.5	3.4	0.5	2.9	ns																			
tPLH	6	^	3.3	0.5	3.9	0.5	3.5	0.5	3	0.5	2.9																				
tPHL	В	Α	3.3	0.5	3.9	0.5	3.5	0.5	3	0.5	2.9	ns																			
^t PZH	ŌĒ	^	2.2	0.5	4.4	0.5	4.3	0.5	4.2	0.5	4.1																				
tPZL	OE	Α	2.2	0.5	4.4	0.5	4.3	0.5	4.2	0.5	4.1	ns																			
t _{PZH}	ŌĒ		4.7	1	9.6	0.5	7.5	0.5	5.1	0.5	4.1																				
tPZL	OE	В	4.7	1	9.6	0.5	7.5	0.5	5.1	0.5	4.1	ns																			
t _{PHZ}	ŌĒ	==				3.4	0.8	5	0.8	5	0.8	5	0.8	5																	
tPLZ		DE A	3.4	0.8	5	0.8	5	0.8	5	0.8	5	ns																			
t _{PHZ}	ŌĒ		4.6	1.2	8.1	1.2	6.7	1	5.1	0.8	5																				
tPLZ		OE	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	OE	OE	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	В	4.6	1.2	8.1	1.2	6.7	1	5.1	0.8	5

operating characteristics, $T_A = 25^{\circ}C$

	PARAME	TER	TEST CONDITIONS	V _{CCA} = V _{CCB} = 1.2 V	V _{CCA} = V _{CCB} = 1.5 V	V _{CCA} = V _{CCB} = 1.8 V	V _{CCA} = V _{CCB} = 2.5 V	V _{CCA} = V _{CCB} = 3.3 V	UNIT		
			CONDITIONS	TYP	TYP	TYP	TYP	TYP			
	A to B	Outputs Enabled		1	1	1	1	2			
C _{pdA} †	AIOB	Outputs Disabled	$C_L = 0,$ f = 10 MHz,			1	1	1	1	1	, F
CpdA	Outputs Enabled	Enabled	$t_r = t_f = 1 \text{ ns}$	12	13	14	15	16	pF		
	B to A Outputs Disabled			1	1	1	1	1			
	A to B	Outputs Enabled		13	13	14	15	16			
Cipt	C _{pdB} † A to B Outputs Disabled Outputs Enabled B to A		C _L = 0,	1	1	1	1	1	pF		
OpdB'			f = 10 MHz, $t_r = t_f = 1 \text{ ns}$	1	1	1	2	2	þΓ		
	D 10 A	Outputs Disabled		1	1	1	1	1			

[†] Power-dissipation capacitance per transceiver



SN74AVC20T245 20-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES566F - MAY 2004 - REVISED APRIL 2005

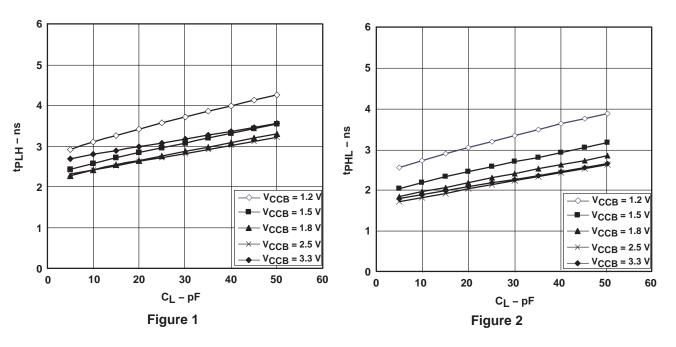
typical total static power consumption ($I_{CCA} + I_{CCB}$)

TABLE 1

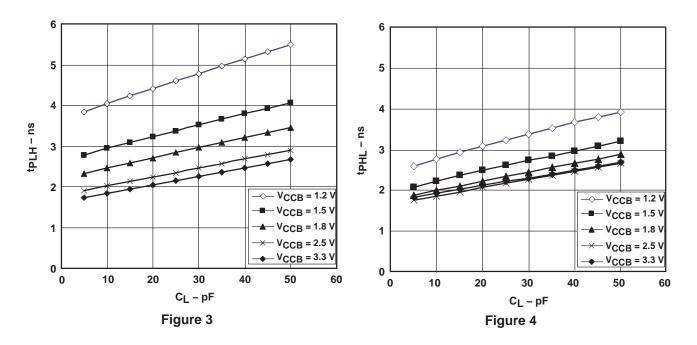
V							
VCCB	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNIT
0 V	0	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5	
1.2 V	< 0.5	< 1	< 1	< 1	< 1	1	
1.5 V	< 0.5	< 1	< 1	< 1	< 1	1	
1.8 V	< 0.5	< 1	< 1	< 1	< 1	< 1	μΑ
2.5 V	< 0.5	1	<1	< 1	< 1	< 1	
3.3 V	< 0.5	1	< 1	< 1	< 1	< 1	

TYPICAL CHARACTERISTICS

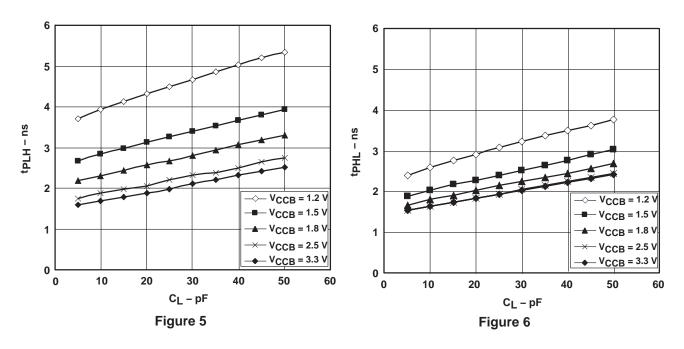
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE $T_A = 25^{\circ}\text{C}$, $V_{CCA} = 1.2 \text{ V}$



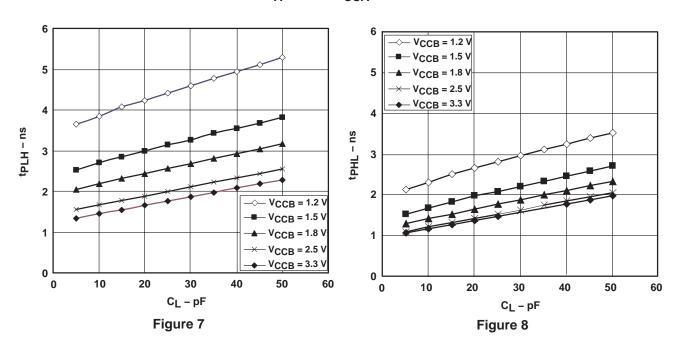
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE $T_A = 25^{\circ}\text{C}$, $V_{CCA} = 1.5 \text{ V}$



TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE $T_A = 25^{\circ}C, V_{CCA} = 1.8 V$

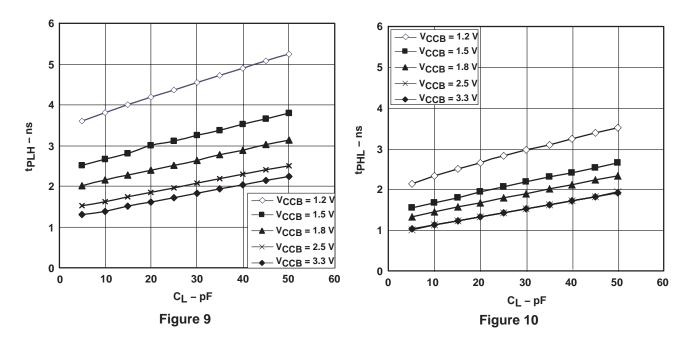


TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE $T_{A}=25^{\circ}\text{C},\,V_{CCA}=2.5\,\text{V}$



SCES566F - MAY 2004 - REVISED APRIL 2005

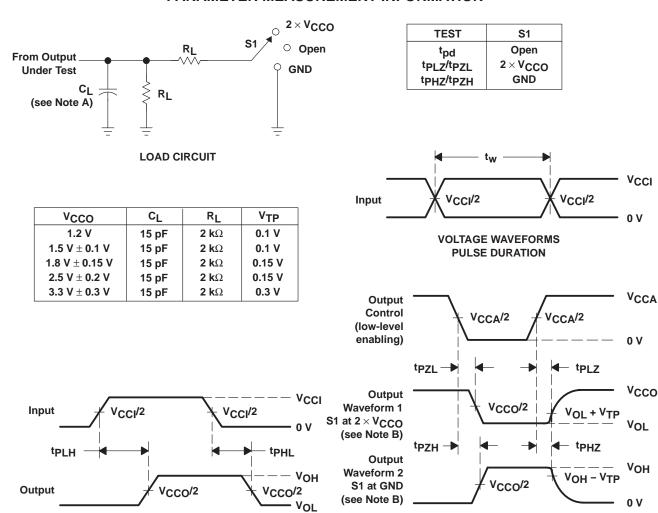
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE $T_A = 25^{\circ}C$, $V_{CCA} = 3.3 \text{ V}$



VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1 V/ns$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. VCCO is the VCC associated with the output port.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES

Figure 11. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

24-Apr-2015

PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74AVC20T245DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC20T245	Samples
74AVC20T245DGVRG4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	WG245	Samples
SN74AVC20T245DGG	ACTIVE	TSSOP	DGG	56	35	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC20T245	Samples
SN74AVC20T245DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVC20T245	Samples
SN74AVC20T245DGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	WG245	Samples
SN74AVC20T245ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	WG245	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

24-Apr-2015

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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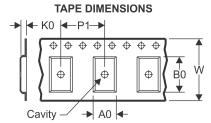
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PACKAGE MATERIALS INFORMATION

www.ti.com 31-Mar-2015

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC20T245DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74AVC20T245DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1
SN74AVC20T245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1

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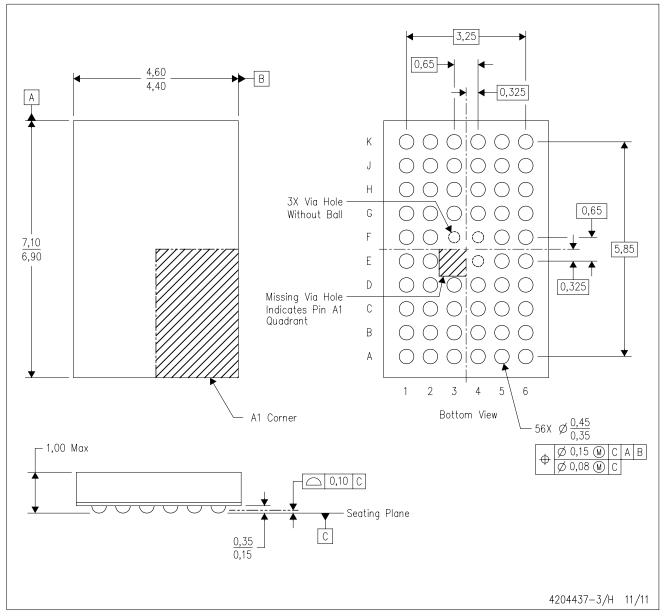


*All dimensions are nominal

Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC20T245DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0
SN74AVC20T245DGVR	TVSOP	DGV	56	2000	367.0	367.0	45.0
SN74AVC20T245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	336.6	336.6	28.6

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

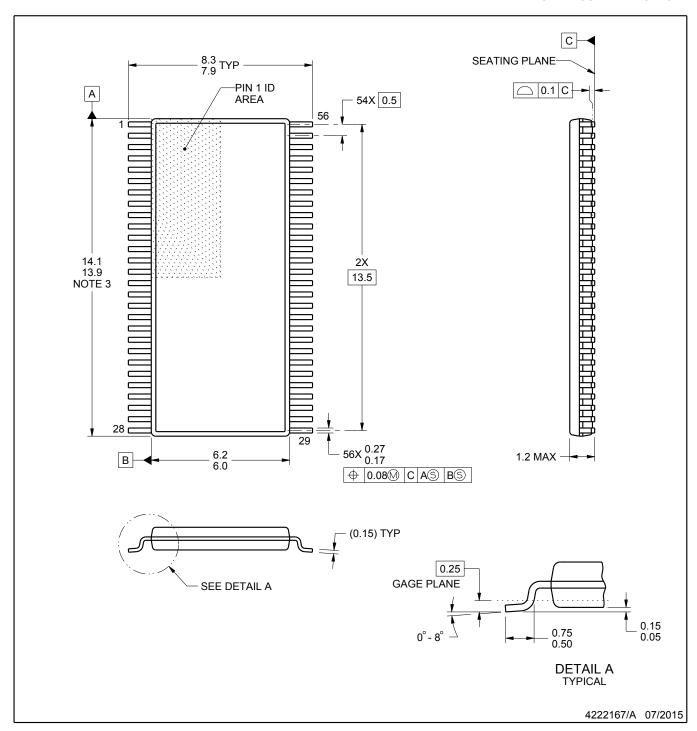
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



NOTES:

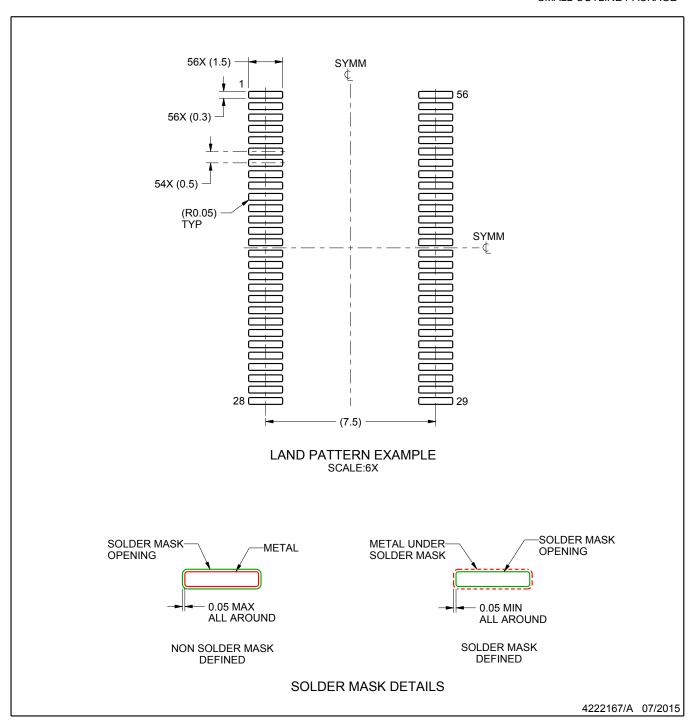
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

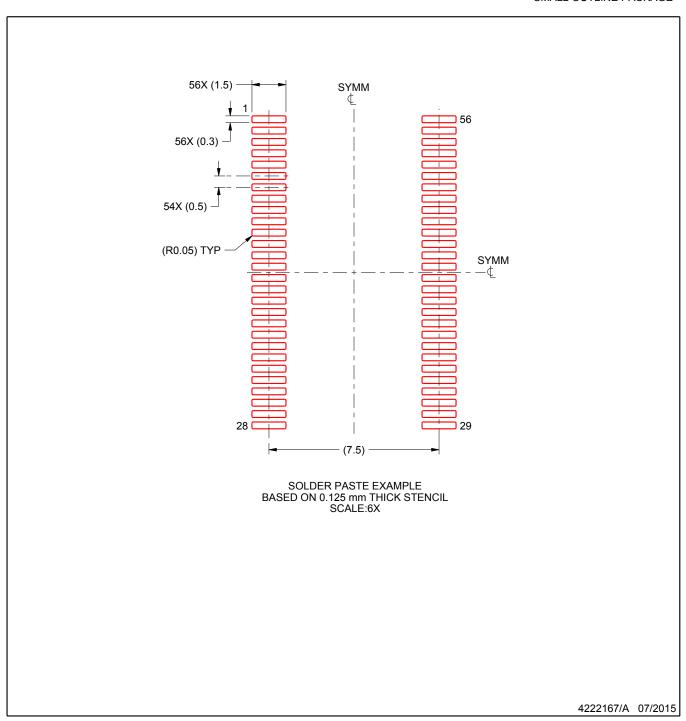


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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